

(19) World Intellectual Property  
Organization  
International Bureau



(43) International Publication Date  
29 September 2005 (29.09.2005)

PCT

(10) International Publication Number  
**WO 2005/091361 A1**

(51) International Patent Classification<sup>7</sup>: **H01L 23/29**,  
21/56

(21) International Application Number:  
PCT/JP2005/004410

(22) International Filing Date: 8 March 2005 (08.03.2005)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:  
2004-079597 19 March 2004 (19.03.2004) JP

(71) Applicant (for all designated States except US): **DOW CORNING TORAY CO., LTD.** [JP/JP]; 1-3, Marunouchi 1-chome., Chiyoda-ku., Tokyo1000005 (JP).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **MORITA, Yoshit-sugu** [JP/JP]; c/o DOW CORNING TORAY CO., LTD., 2-2, Chigusakaigan, Ichihara-shi, Chiba, 2990108 (JP). **NAKANISHI, Junji** [JP/JP]; c/o DOW CORNING

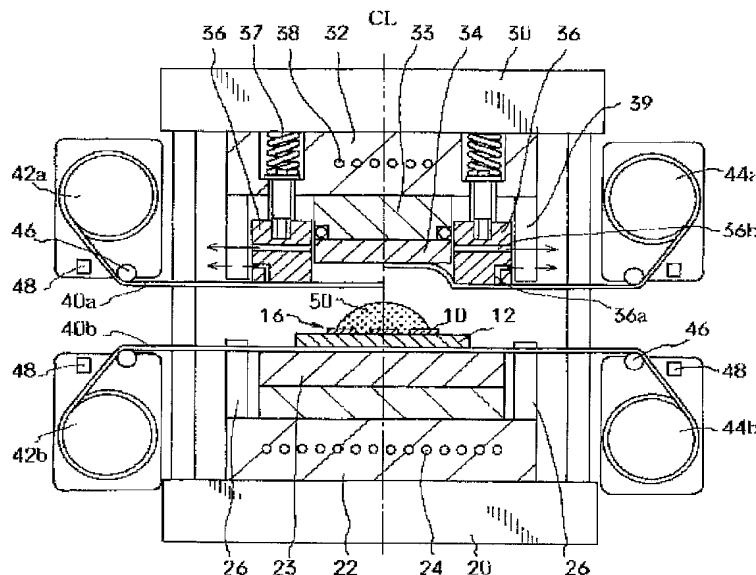
TORAY CO., LTD., 2-2, Chigusakaigan, Ichihara-shi, Chiba, 2990108 (JP). **MINE, Katsutoshi** [JP/JP]; 7-20-2, Aobadai, Ichihara-shi, Chiba, 2990117 (JP).

(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

[Continued on next page]

(54) Title: SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING THEREOF



(57) Abstract: A method of manufacturing a semiconductor device sealed in a cured silicone body by placing an unsealed semiconductor device into a mold and subjecting a curable liquid silicone composition that fills the spaces between the mold and the unsealed semiconductor device to compression molding under a predetermined molding temperature, wherein the curable liquid silicone composition has viscosity of 90 Pa·s or less at room temperature, a time interval from the moment directly after measurement of a torque with a curometer at the molding temperature to the moment when the torque reached 1 kgf·cm being not less than 1 min., while the time

WO 2005/091361 A1



---

**Published:**

— with international search report

*For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.*